

PATENT ASSIGNMENT

Electronic Version v1.1
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SUBMISSION TYPE:	NEW ASSIGNMENT						
NATURE OF CONVEYANCE:	ASSIGNMENT						
CONVEYING PARTY DATA							
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Robert T. Hirahara</td> <td>09/16/2008</td> </tr> <tr> <td>Vijay D. Parkhe</td> <td>09/11/2008</td> </tr> </tbody> </table>		Name	Execution Date	Robert T. Hirahara	09/16/2008	Vijay D. Parkhe	09/11/2008
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Robert T. Hirahara	09/16/2008						
Vijay D. Parkhe	09/11/2008						
RECEIVING PARTY DATA							
Name:	APPLIED MATERIALS, INC.						
Street Address:	3050 Bowers Avenue						
City:	Santa Clara						
State/Country:	CALIFORNIA						
Postal Code:	95054						
PROPERTY NUMBERS Total: 1							
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13297203</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13297203		
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Application Number:	13297203						
CORRESPONDENCE DATA							
Fax Number:	(713)623-4846						
Phone:	7136234844						
Email:	psdocketing@pattersonsheridan.com, nhouston@pattersonsheridan.com						
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i>							
Correspondent Name:	PATTERSON & SHERIDAN, LLP - - APPM/TX						
Address Line 1:	3040 POST OAK BOULEVARD, SUITE 1500						
Address Line 4:	HOUSTON, TEXAS 77056						
ATTORNEY DOCKET NUMBER:	APPM/012945.D1/NHOUSTON						
NAME OF SUBMITTER:	Keith M. Tackett						
Total Attachments: 4 source=012945D1_Assignment_EF#page1.tif source=012945D1_Assignment_EF#page2.tif source=012945D1_Assignment_EF#page3.tif source=012945D1_Assignment_EF#page4.tif							

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COPY

Atty. Dkt. No. APPM/012945/AGS/SPARES/ESONG

ASSIGNMENT FOR APPLICATION FOR PATENT

WHEREAS:

Names and Addresses of Inventors:

1)	ROBERT T. HIRAHARA 952 S. 11th Street, Unit 336 San Jose, CA 95112	2)	VIJAY D. PARKHE 4054 Bouquet Park Lane San Jose, CA 95135
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(hereinafter referred to as Assignors), have invented a certain invention entitled:

ELECTROSTATIC CHUCK ELECTRICAL BALANCING CIRCUIT REPAIR

enclosed herewith or for which application for Letters Patent in the United States was filed on September 5, 2008,
under Serial No. 12/205,428, executed on even date herewith; and

WHEREAS, Applied Materials, Inc., a corporation of the State of Delaware, having a place of business at 3050 Bowers Avenue, Santa Clara, California 95054 (hereinafter referred to as Assignee), is desirous of acquiring the entire right, title and interest in and to said application (hereinafter referred to as Application), and the invention disclosed therein (hereinafter referred to as Invention), and in and to all embodiments of the Invention, heretofore conceived, made or discovered by said Assignors, and in and to any and all patents, inventor's certificates and other forms of protection (hereinafter referred to as Patents) thereon granted in any and all countries and groups of countries.

NOW, THEREFORE, in consideration of good and valuable consideration acknowledged by said Assignors to have been received in full from said Assignee:

1. Said Assignors hereby sell, assign, transfer and convey to Assignee the full and exclusive right, title and interest (a) in and to said Application and said Invention; (b) in and to all rights to apply for patents on said Invention in any and all countries pursuant to the International Convention for the Protection of Industrial Property or otherwise; (c) in and to any and all Applications filed and any and all Patents granted on said Invention in any and all countries and groups of countries, including each and every Application filed and each and every Patent granted on any application which is a conventional, division, substitution, or continuation of said Application; and (d) in and to each and every reissue or extension of any of said Patents.

2. Said Assignors hereby covenant and agree to cooperate with said Assignee to enable said Assignee to enjoy to the fullest extent the right, title and interest to said Invention herein conveyed in any and all countries and groups of

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PATENT

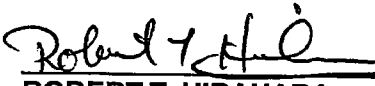
REEL: 027643 FRAME: 0786

countries. Such cooperation by said Assignors shall include prompt production of pertinent facts and documents, giving testimony, execution of petitions, oaths, specifications, declarations or other papers, and other assistance all to the extent deemed necessary or desirable by said Assignee (a) for perfecting in said Assignee the right, title and interest herein conveyed; (b) for prosecuting any of said applications; (c) for filing and prosecuting conventional, substitute, divisional, continuing or additional applications covering said Invention; (d) for filing and prosecuting applications for reissuance of any of said Patents; (e) for interference or other priority proceedings involving said Invention; and (f) for legal proceedings involving said Invention and any application therefor and any Patents granted thereon, including without limitation opposition proceedings, cancellation proceedings, priority contests, public use proceedings, infringement actions and court actions; provided, however, that the expense incurred by said Assignors in providing such cooperation shall be paid for by said Assignee.

3. The term and covenants of this agreement shall inure to the benefit of said Assignee, its successors, assigns and other legal representatives, and shall be binding upon said Assignors, their respective heirs, legal representatives and assigns.

4. Said Assignors hereby warrant and represent that they have not entered and will not enter into any assignment, contract, or understanding in conflict herewith.

IN WITNESS WHEREOF, the said Assignors have executed and delivered this instrument to said Assignee on the dates indicated below.

1) 9/16/08 (DATE) 
ROBERT T. HIRAHARA

2) _____ (DATE) _____
VIJAY D. PARKHE

COPY

Atty. Dkt. No. APPM/012945/AGS/SPARES/ESONG

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IN WITNESS WHEREOF, the said Assignors have executed and delivered this instrument to said Assignee on the dates indicated below.

1) _____ (DATE)

ROBERT T. HIRAHARA

2) 9/11/2008 (DATE)

VIJAY D. PARKHE